



100% Material Declaration Data Sheet HQG208

PK119 (v1.2) September 28, 2006

Material Declaration Data Sheet

Average Weight: 10.943 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.16981	1.55%
	Silicon	7440-21-3	100.00		0.169814	
Die Attach Material					0.01531	0.14%
	Resin	Trade Secret	25.00		0.003828	
	Silver	7440-22-4	75.00		0.011483	
Mold Compound					3.24216	29.63%
	Epoxy Resin (EP)	Trade Secret	16.00		0.518746	
	Silica	60676-86-0	84.00		2.723414	
Leadframe					0.37676	3.44%
	Copper	7440-50-8	99.25		0.373939	
	Chromium	7440-47-3	0.30		0.001130	
	Tin	7440-31-5	0.25		0.000942	
	Zinc	7440-66-6	0.20		0.000754	
Leadframe Plating					0.001560	0.01%
	Silver	7440-22-4	100.00		0.001560	
Heat Sink					7.08725	64.76%
	Copper	7440-50-8	100.00		7.08725	
Ext. Heat Sink Plating					0.00547	0.05%
	Nickel	7440-02-0	100.00		0.005471	
Bond Wire					0.01153	0.11%
	Gold	7440-57-5	99.04		0.011417	
	Palladium	7440-05-3	0.9500		0.000110	
Ext. Plating					0.03346	0.31%
	Tin	7440-31-5	100.00		0.03346	

PK119 (v1.2) September 28, 2006

www.xilinx.com

1

© 2006 Xilinx, Inc. All rights reserved. All Xilinx trademarks, registered trademarks, patents, and disclaimers are as listed at <http://www.xilinx.com/legal.htm>.
All other trademarks and registered trademarks are the property of their respective owners. All specifications are subject to change without notice.
Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

www.BDTIC.com/XILINX

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.